PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HSIN-YEN HUANG	09/06/2019
SHAO-KUAN LEE	09/06/2019
CHENG-CHIN LEE	09/06/2019
HAI-CHING CHEN	09/06/2019
SHAU-LIN SHUE	09/06/2019

RECEIVING PARTY DATA

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City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16577079

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ATTORNEY DOCKET NUMBER:	2018-1155/24061.3801US01
NAME OF SUBMITTER:	DAVID M. O'DELL
SIGNATURE:	/David M. O'Dell/
DATE SIGNED:	09/20/2019

Total Attachments: 3
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77 (5)

Docket No.: P20181155US00/24061.3801US01
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1) Hsin-Yen Huang of New Taipei City, Taiwan, Republic of China

(2) Shao-Kuan Lee of Hsinchu, Taiwan, Republic of China

(3) Cheng-Chin Lee of Hsinchu, Taiwan, Republic of China

(4) Hai-Ching Chen of Hsinchu City, Taiwan, Republic of China

(5) Shau-Lin Shue of Hsinchu, Taiwan, Republic of China

SELECTIVE DEPOSITION FOR INTEGRATED CIRCUIT INTERCONNECT STRUCTURES

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
__X__ filed on 09-20-2019 and assigned application number 16/577,079; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Hsin-Yen Huang

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Dated: 2019.9.6

Hsin-Yen Huang
Inventor Signature

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Dated: 2019.9.6.

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Dated: 2019. 9. 6

Inventor Signature
